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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	17110
Number of Logic Elements/Cells	362000
Total RAM Bits	19822592
Number of I/O	704
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-BBGA
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxmb3g4f40c5g

Table 1-21: Transceiver Clocks Specifications for Arria V GX and SX Devices

Symbol/Description	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
		Min	Typ	Max	Min	Typ	Max	
`fixedclk` clock frequency	PCIe Receiver Detect	—	125	—	—	125	—	MHz
Transceiver Reconfiguration Controller IP (`mgmt_clk_clk`) clock frequency	—	75	—	125	75	—	125	MHz

Table 1-22: Receiver Specifications for Arria V GX and SX Devices

Symbol/Description	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
		Min	Typ	Max	Min	Typ	Max	
Supported I/O standards	1.5 V PCML, 2.5 V PCML, LVPECL, and LVDS							
Data rate[28]	—	611	—	6553.6	611	—	3125	Mbps
Absolute V_{MAX} for a receiver pin[29]	—	—	—	1.2	—	—	1.2	V
Absolute V_{MIN} for a receiver pin	—	–0.4	—	—	–0.4	—	—	V
Maximum peak-to-peak differential input voltage V_{ID} (diff p-p) before device configuration	—	—	—	1.6	—	—	1.6	V
Maximum peak-to-peak differential input voltage V_{ID} (diff p-p) after device configuration	—	—	—	2.2	—	—	2.2	V

(28) To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.
(29) The device cannot tolerate prolonged operation at this absolute maximum.

Table 1-31: Transceiver-FPGA Fabric Interface Specifications for Arria V GT and ST Devices

Symbol/Description	Transceiver Speed Grade 3		Unit
	Min	Max	
Interface speed (PMA direct mode)	50	153.6[56], 161[57]	MHz
Interface speed (single-width mode)	25	187.5	MHz
Interface speed (double-width mode)	25	163.84	MHz

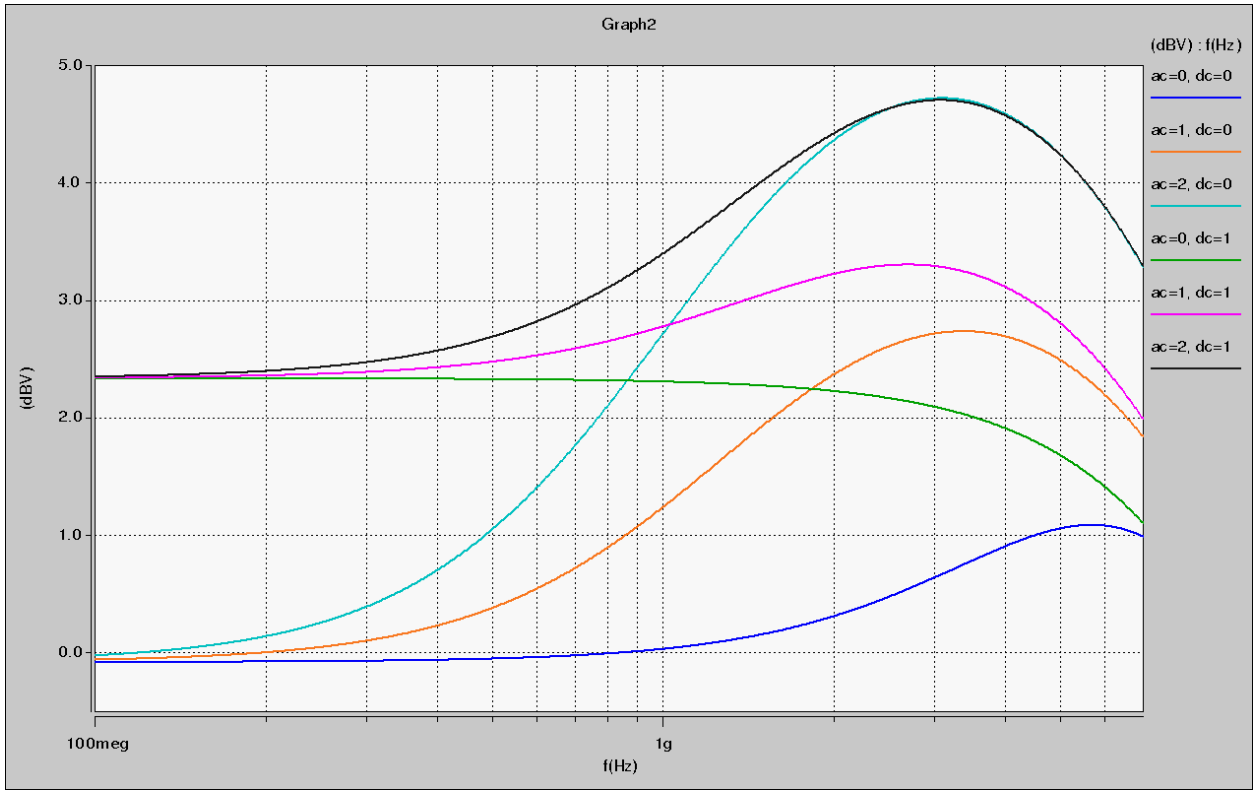
Related Information

- **CTLE Response at Data Rates > 3.25 Gbps across Supported AC Gain and DC Gain** on page 1-35
- **CTLE Response at Data Rates ≤ 3.25 Gbps across Supported AC Gain and DC Gain** on page 1-36

[56] The maximum frequency when core transceiver local routing is selected.
[57] The maximum frequency when core transceiver network routing (GCLK, RCLK, or PCLK) is selected.

CTLE Response at Data Rates > 3.25 Gbps across Supported AC Gain and DC Gain

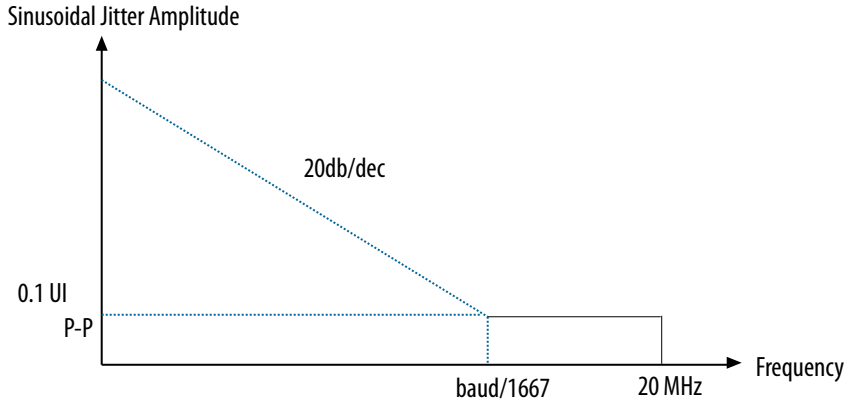
Figure 1-2: Continuous Time-Linear Equalizer (CTLE) Response at Data Rates > 3.25 Gbps across Supported AC Gain and DC Gain for Arria V GX, GT, SX, and ST Devices



Symbol	Condition	–I3, –C4			–I5, –C5			–C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
	SERDES factor J ≥ 8[76][78], LVDS TX with RX DPA	[77]	—	1600	[77]	—	1500	[77]	—	1250	Mbps
	SERDES factor J = 1 to 2, Uses DDR Registers	[77]	—	[79]	[77]	—	[79]	[77]	—	[79]	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Network - f_{HSDR} (data rate)[80]	SERDES factor J = 4 to 10[81]	[77]	—	945	[77]	—	945	[77]	—	945	Mbps
Emulated Differential I/O Standards with One External Output Resistor Network - f_{HSDR} (data rate)[80]	SERDES factor J = 4 to 10[81]	[77]	—	200	[77]	—	200	[77]	—	200	Mbps
$t_{x\ Jitter}$ -True Differential I/O Standards	Total Jitter for Data Rate 600 Mbps – 1.25 Gbps	—	—	160	—	—	160	—	—	160	ps
	Total Jitter for Data Rate < 600 Mbps	—	—	0.1	—	—	0.1	—	—	0.1	UI

(78) The V_{CC} and V_{CCP} must be on a separate power layer and a maximum load of 5 pF for chip-to-chip interface.
(79) The maximum ideal data rate is the SERDES factor (J) x the PLL maximum output frequency (f_{OUT}), provided you can close the design timing and the signal integrity simulation is clean.
(80) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine the leftover timing margin.
(81) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

Figure 1-6: LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate Less than 1.25 Gbps



DLL Frequency Range Specifications

Table 1-43: DLL Frequency Range Specifications for Arria V Devices

Parameter	–I3, –C4	–I5, –C5	–C6	Unit
DLL operating frequency range	200 – 667	200 – 667	200 – 667	MHz

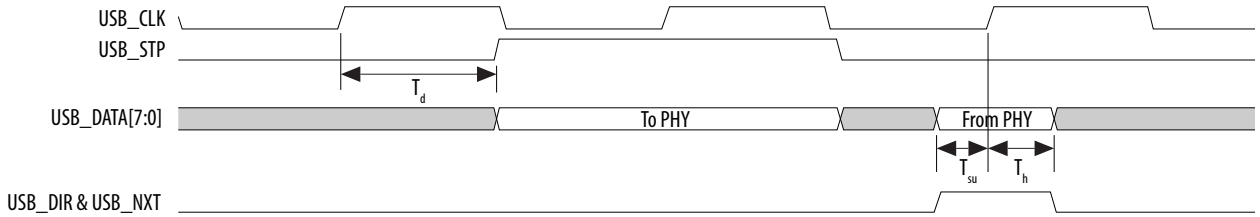
DQS Logic Block Specifications

Table 1-44: DQS Phase Shift Error Specifications for DLL-Delayed Clock (t_{DQS_PSERR}) for Arria V Devices

This error specification is the absolute maximum and minimum error.

Number of DQS Delay Buffer	–I3, –C4	–I5, –C5	–C6	Unit
2	40	80	80	ps

Figure 1-12: USB Timing Diagram

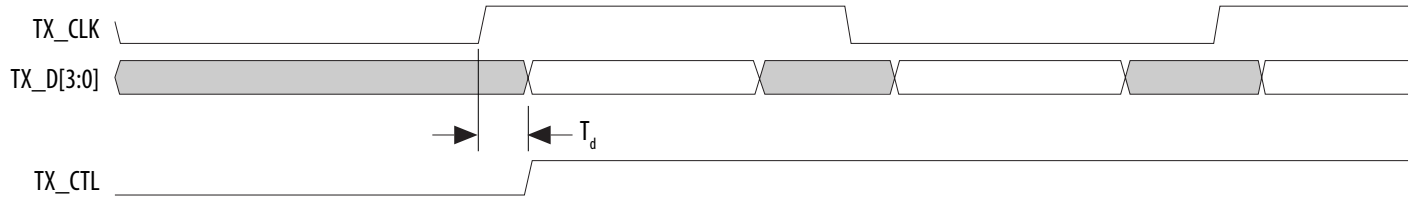


Ethernet Media Access Controller (EMAC) Timing Characteristics

Table 1-56: Reduced Gigabit Media Independent Interface (RGMII) TX Timing Requirements for Arria V Devices

Symbol	Description	Min	Typ	Max	Unit
T_{clk} (1000Base-T)	TX_CLK clock period	—	8	—	ns
T_{clk} (100Base-T)	TX_CLK clock period	—	40	—	ns
T_{clk} (10Base-T)	TX_CLK clock period	—	400	—	ns
$T_{dutycycle}$	TX_CLK duty cycle	45	—	55	%
T_d	TX_CLK to TXD/TX_CTL output data delay	–0.85	—	0.15	ns

Figure 1-13: RGMII TX Timing Diagram



Symbol	Description	Min	Max	Unit
T_{dh} (89)	Data to write enable hold time	5	—	ns
T_{cea}	Chip enable to data access time	—	25	ns
T_{rea}	Read enable to data access time	—	16	ns
T_{rhz}	Read enable to data high impedance	—	100	ns
T_{rr}	Ready to read enable low	20	—	ns

Figure 1-17: NAND Command Latch Timing Diagram

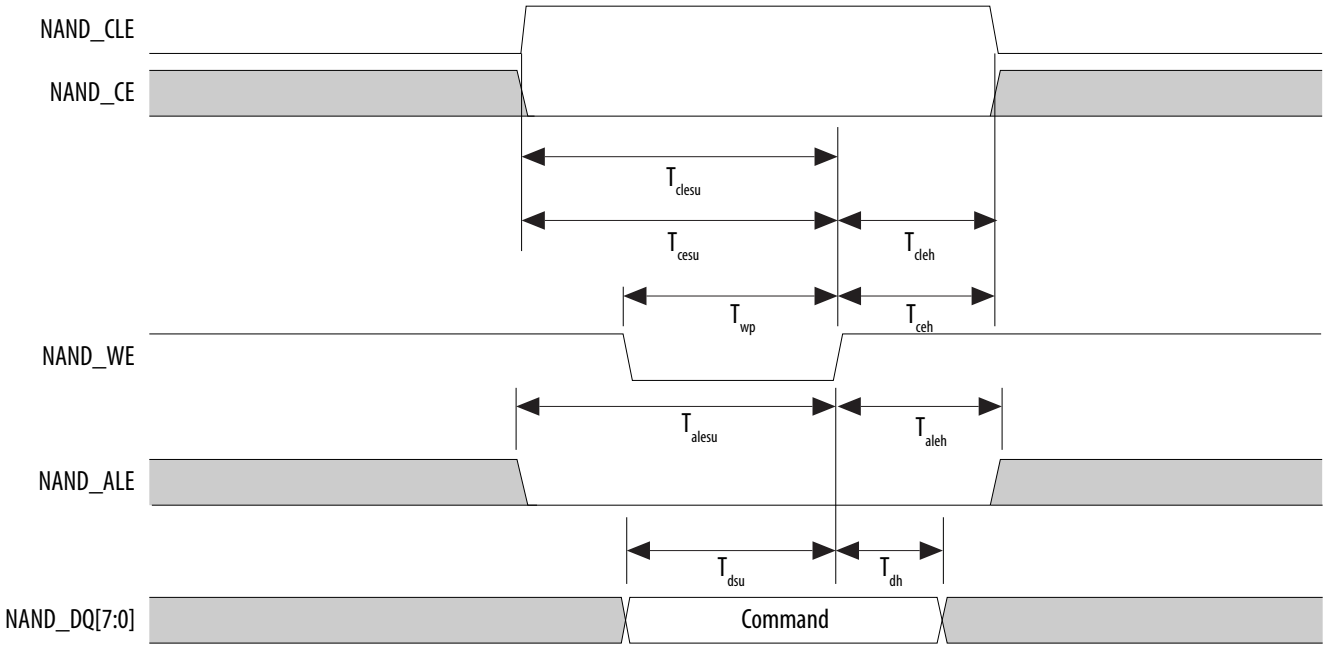


Figure 1-18: NAND Address Latch Timing Diagram

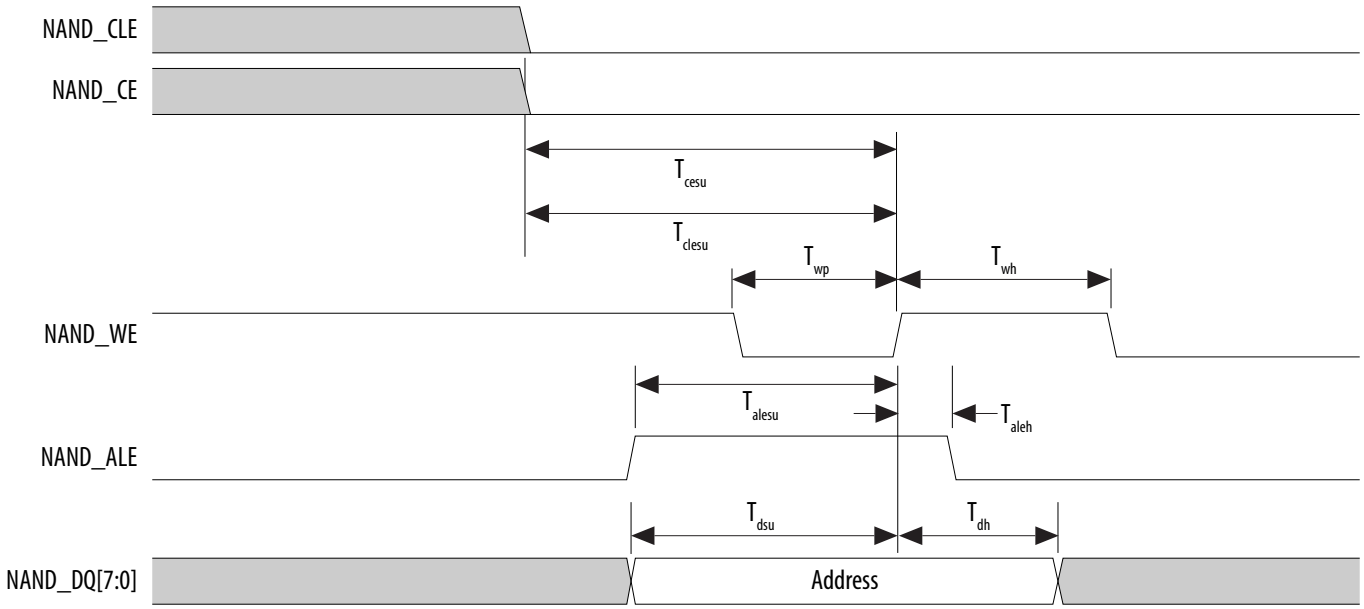
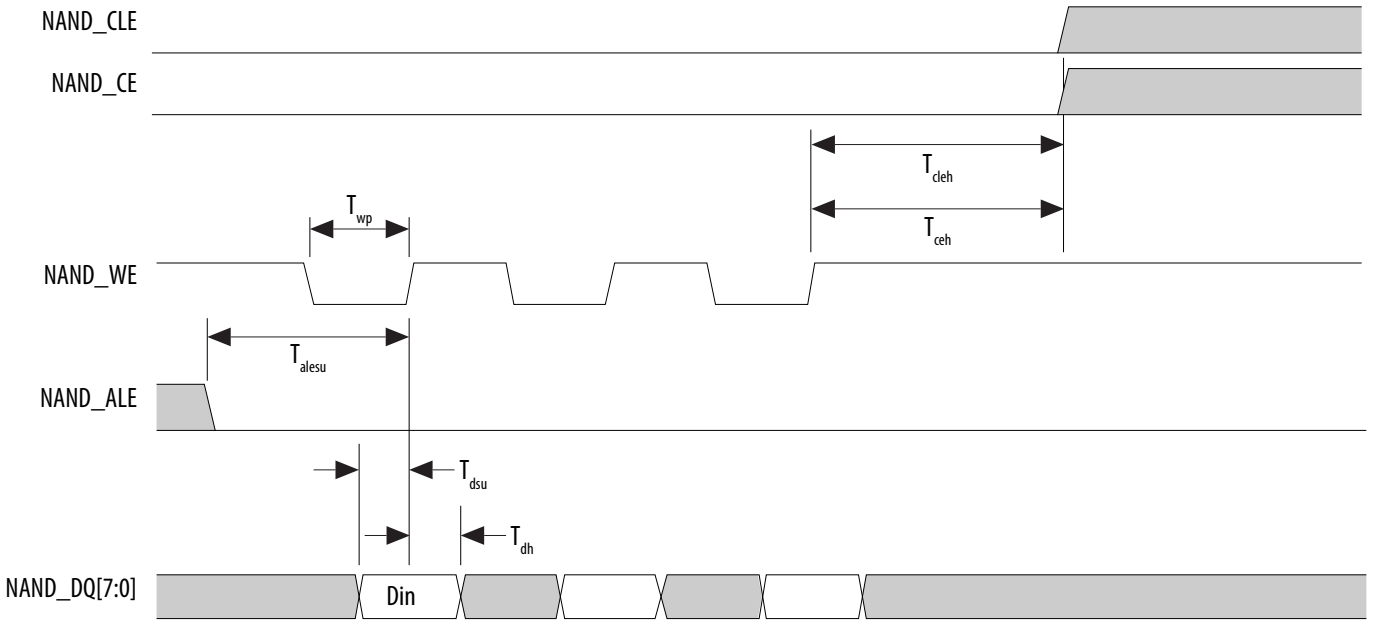


Figure 1-19: NAND Data Write Timing Diagram



Symbol	Parameter	Minimum	Maximum	Unit
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (T_{init} × CLKUSR period)	—	—
T_{init}	Number of clock cycles required for device initialization	8,576	—	Cycles

Related Information

FPP Configuration Timing
Provides the FPP configuration timing waveforms.

AS Configuration Timing

Table 1-68: AS Timing Parameters for AS ×1 and ×4 Configurations in Arria V Devices

The minimum and maximum numbers apply to both the internal oscillator and CLKUSR when either one is used as the clock source for device configuration.

The t_{CF2CD}, t_{CF2ST0}, t_{CFG}, t_{STATUS}, and t_{CF2ST1} timing parameters are identical to the timing parameters for passive serial (PS) mode listed in PS Timing Parameters for Arria V Devices table. You can obtain the t_{CF2ST1} value if you do not delay configuration by externally holding nSTATUS low.

Symbol	Parameter	Minimum	Maximum	Unit
t_{CO}	DCLK falling edge to the AS_DATA0/ASDO output	—	2	ns
t_{SU}	Data setup time before the falling edge on DCLK	1.5	—	ns
t_{DH}	Data hold time after the falling edge on DCLK	0	—	ns
t_{CD2UM}	CONF_DONE high to user mode	175	437	µs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (T_{init} × CLKUSR period)	—	—
T_{init}	Number of clock cycles required for device initialization	8,576	—	Cycles

Symbol	Parameter	Minimum	Maximum	Unit
t_{CF2CK}[105]	nCONFIG high to first rising edge on DCLK	1506	—	µs
t_{ST2CK}[105]	nSTATUS high to first rising edge of DCLK	2	—	µs
t_{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t_{DH}	DATA[] hold time after rising edge on DCLK	0	—	ns
t_{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
t_{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t_{CLK}	DCLK period	$1/f_{MAX}$	—	s
f_{MAX}	DCLK frequency	—	125	MHz
t_{CD2UM}	CONF_DONE high to user mode[106]	175	437	µs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (T_{init} \times$ CLKUSR period)	—	—
T_{init}	Number of clock cycles required for device initialization	8,576	—	Cycles

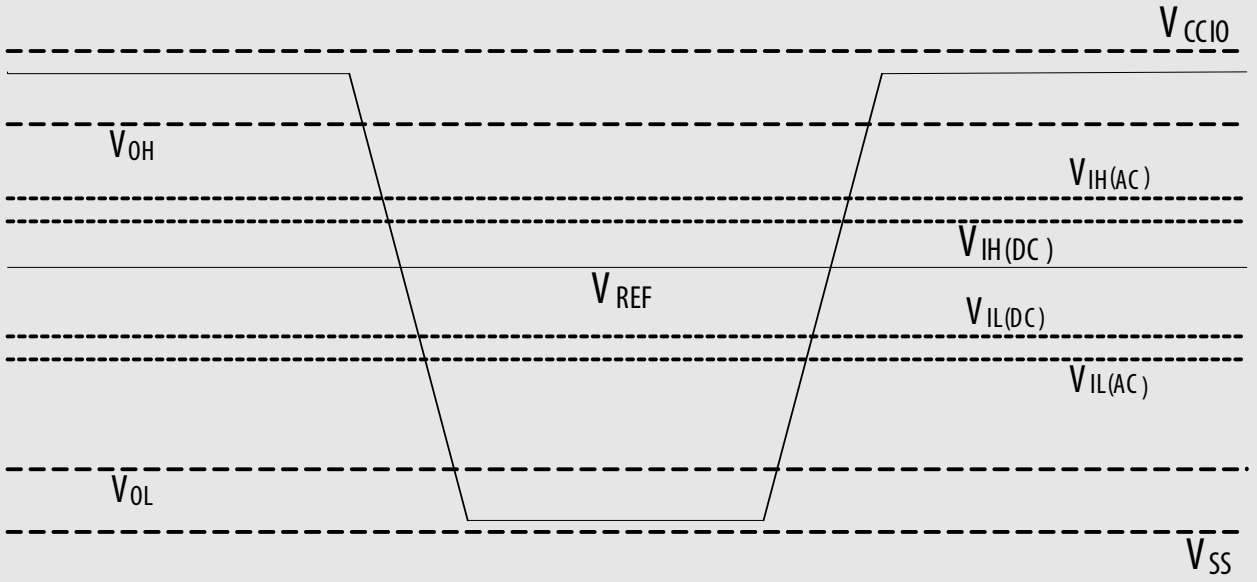
Related Information

PS Configuration Timing

Provides the PS configuration timing waveform.

(105) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

(106) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

Term	Definition
Single-ended voltage referenced I/O standard	The JEDEC standard for the SSTL and HSTL I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state. The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing. Single-Ended Voltage Referenced I/O Standard 
t_C	High-speed receiver/transmitter input and output clock period.
TCCS (channel-to-channel-skew)	The timing difference between the fastest and slowest output edges, including the t_{CO} variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the Timing Diagram figure under SW in this table).
t_{DUTY}	High-speed I/O block—Duty cycle on high-speed transmitter output clock.

Term	Definition
V_{OX}	Output differential cross point voltage
W	High-speed I/O block—Clock boost factor

Document Revision History

Date	Version	Changes

December 2016	2016.12.09	• Updated V_{ICM} (AC coupled) specifications in Receiver Specifications for Arria V GX and SX Devices table.
		• Added maximum specification for T_d in Management Data Input/Output (MDIO) Timing Requirements for Arria V Devices table.
		• Updated T_{init} specifications in the following tables:
		  • FPP Timing Parameters When DCLK-to-DATA[] Ratio is 1 for Arria V Devices
		  • FPP Timing Parameters When DCLK-to-DATA[] Ratio is >1 for Arria V Devices
		  • AS Timing Parameters for AS ×1 and ×4 Configurations in Arria V Devices
		  • PS Timing Parameters for Arria V Devices

June 2016	2016.06.10	• Changed pin capacitance to maximum values.
		• Updated SPI Master Timing Requirements for Arria V Devices table.
		  • Added T_{su} and T_h specifications.
		  • Removed T_{dinmax} specifications.
		• Updated SPI Master Timing Diagram.
		• Updated T_{clk} spec from maximum to minimum in I^2C Timing Requirements for Arria V Devices table.

The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle.

For example, a signal that overshoots to 3.95 V can be at 3.95 V for only ~21% over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~2 years.

Table 2-4: Maximum Allowed Overshoot During Transitions for Arria V GZ Devices

Symbol	Description	Condition (V)	Overshoot Duration as % @ T_J = 100°C	Unit
Vi (AC)	AC input voltage	3.8	100	%
		3.85	64	%
		3.9	36	%
		3.95	21	%
		4	12	%
		4.05	7	%
		4.1	4	%
		4.15	2	%
		4.2	1	%

Recommended Operating Conditions

Table 2-5: Recommended Operating Conditions for Arria V GZ Devices

Power supply ramps must all be strictly monotonic, without plateaus.

Symbol	Description	Condition	Minimum(114)	Typical	Maximum (114)	Unit
V_{CC}	Core voltage and periphery circuitry power supply (115)	—	0.82	0.85	0.88	V

(114) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

(115) The V_{CC} core supply must be set to 0.9 V if the Partial Reconfiguration (PR) feature is used.

Symbol	Parameter	Min	Typ	Max	Unit
f_{OUT} (169)	Output frequency for an internal global or regional clock (C3, I3L speed grade)	—	—	650	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grade)	—	—	580	MHz
f_{OUT_EXT} (169)	Output frequency for an external clock output (C3, I3L speed grade)	—	—	667	MHz
	Output frequency for an external clock output (C4, I4 speed grade)	—	—	533	MHz
$t_{OUTDUTY}$	Duty cycle for a dedicated external clock output (when set to 50%)	45	50	55	%
t_{FCOMP}	External feedback clock compensation time	—	—	10	ns
$f_{DYCONFIGCLK}$	Dynamic configuration clock for `mgmt_clk` and `scanclk`	—	—	100	MHz
t_{LOCK}	Time required to lock from the end-of-device configuration or deassertion of `areset`	—	—	1	ms
t_{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/ delays)	—	—	1	ms
f_{CLBW}	PLL closed-loop low bandwidth	—	0.3	—	MHz
	PLL closed-loop medium bandwidth	—	1.5	—	MHz
	PLL closed-loop high bandwidth (170)	—	4	—	MHz
t_{PLL_PSERR}	Accuracy of PLL phase shift	—	—	±50	ps
t_{ARESET}	Minimum pulse width on the `areset` signal	10	—	—	ns

(169) This specification is limited by the lower of the two: I/O f_{MAX} or f_{OUT} of the PLL.
(170) High bandwidth PLL settings are not supported in external feedback mode.

Memory	Mode	Resources Used		Performance				Unit
		ALUTs	Memory	C3	C4	I3L	I4	
M20K Block	Single-port, all supported widths	0	1	650	550	500	450	MHz
	Simple dual-port, all supported widths	0	1	650	550	500	450	MHz
	Simple dual-port with the read-during-write option set to **Old Data**, all supported widths	0	1	455	400	455	400	MHz
	Simple dual-port with ECC enabled, 512 × 32	0	1	400	350	400	350	MHz
	Simple dual-port with ECC and optional pipeline registers enabled, 512 × 32	0	1	500	450	500	450	MHz
	True dual port, all supported widths	0	1	650	550	500	450	MHz
	ROM, all supported widths	0	1	650	550	500	450	MHz

Temperature Sensing Diode Specifications

Table 2-37: Internal Temperature Sensing Diode Specification

Temperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
–40°C to 100°C	±8°C	No	1 MHz, 500 kHz	< 100 ms	8 bits	8 bits

Table 2-38: External Temperature Sensing Diode Specifications for Arria V GZ Devices

Description	Min	Typ	Max	Unit
I_{bias}, diode source current	8	—	200	µA
$V_{bias,}$ voltage across diode	0.3	—	0.9	V
Series resistance	—	—	< 1	Ω

Description	Min	Typ	Max	Unit
Diode ideality factor	1.006	1.008	1.010	—

Periphery Performance

I/O performance supports several system interfaces, such as the **LVDS** high-speed I/O interface, external memory interface, and the **PCI/PCI-X** bus interface. General-purpose I/O standards such as 3.3-, 2.5-, 1.8-, and 1.5-**LVTTL/LVCMOS** are capable of a typical 167 MHz and 1.2-**LVCMOS** at 100 MHz interfacing frequency with a 10 pF load.

Note: The actual achievable frequency depends on design- and system-specific factors. Ensure proper timing closure in your design and perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.

High-Speed I/O Specification

High-Speed Clock Specifications

Table 2-39: High-Speed Clock Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.

For LVDS applications, you must use the PLLs in integer PLL mode.

Arria V GZ devices support the following output standards using true LVDS output buffer types on all I/O banks.

- True RSDS output standard with data rates of up to 230 Mbps
- True mini-LVDS output standard with data rates of up to 340 Mbps

Number of DQS Delay Buffers	C3, I3L	C4, I4	Unit
4	120	128	ps

Memory Output Clock Jitter Specifications

Table 2-50: Memory Output Clock Jitter Specification for Arria V GZ Devices

The clock jitter specification applies to the memory output clock pins generated using differential signal-splitter and DDIO circuits clocked by a PLL output routed on a PHY, regional, or global clock network as specified. Altera recommends using PHY clock networks whenever possible.

The clock jitter specification applies to the memory output clock pins clocked by an integer PLL.

The memory output clock jitter is applicable when an input jitter of 30 ps peak-to-peak is applied with bit error rate (BER) -12, equivalent to 14 sigma.

Clock Network	Parameter	Symbol	C3, I3L		C4, I4		Unit
			Min	Max	Min	Max	
Regional	Clock period jitter	$t_{JIT(per)}$	–55	55	–55	55	ps
	Cycle-to-cycle period jitter	$t_{JIT(cc)}$	–110	110	–110	110	ps
	Duty cycle jitter	$t_{JIT(duty)}$	–82.5	82.5	–82.5	82.5	ps
Global	Clock period jitter	$t_{JIT(per)}$	–82.5	82.5	–82.5	82.5	ps
	Cycle-to-cycle period jitter	$t_{JIT(cc)}$	–165	165	–165	165	ps
	Duty cycle jitter	$t_{JIT(duty)}$	–90	90	–90	90	ps
PHY Clock	Clock period jitter	$t_{JIT(per)}$	–30	30	–35	35	ps
	Cycle-to-cycle period jitter	$t_{JIT(cc)}$	–60	60	–70	70	ps
	Duty cycle jitter	$t_{JIT(duty)}$	–45	45	–56	56	ps

Table 2-55: DCLK-to-DATA[] Ratio for Arria V GZ Devices

Depending on the DCLK-to-DATA[] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA[] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Arria V GZ devices use the additional clock cycles to decrypt and decompress the configuration data.

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
FPP ×8	Disabled	Disabled	1
	Disabled	Enabled	1
	Enabled	Disabled	2
	Enabled	Enabled	2
FPP ×16	Disabled	Disabled	1
	Disabled	Enabled	2
	Enabled	Disabled	4
	Enabled	Enabled	4
FPP ×32	Disabled	Disabled	1
	Disabled	Enabled	4
	Enabled	Disabled	8
	Enabled	Enabled	8

Term	Definition
V_{OCM}	Output common mode voltage—The common mode of the differential signal at the transmitter.
V_{OD}	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
V_{SWING}	Differential input voltage
V_X	Input differential cross point voltage
V_{OX}	Output differential cross point voltage
W	High-speed I/O block—clock boost factor

Document Revision History

Date	Version	Changes
February 2017	2017.02.10	• Changed the minimum value for t_{CD2UMC} in the “FPP Timing Parameters for Arria V GZ Devices When the DCLK-to-DATA[] Ratio is 1” table. • Changed the minimum value for t_{CD2UMC} in the "FPP Timing Parameters for Arria V GZ Devices When the DCLK-to-DATA[] Ratio is >1" table. • Changed the minimum value for t_{CD2UMC} in the "AS Timing Parameters for AS x1 and AS x4 Configurations in Arria V GZ Devices" table. • Changed the minimum value for t_{CD2UMC} in the "PS Timing Parameters for Arria V GZ Devices" table. • Changed the minimum number of clock cycles value in the "Initialization Clock Source Option and the Maximum Frequency for Arria V GZ Devices" table.